



Material Content Data Sheet



Sales Product Name				IPU80R2K8CE		Issued		27. September 2017	
MA#				MA001126788					
Package				PG-TO251-3-341		Weight*		381.62 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.280	0.60	0.60	5974	5974	
leadframe	non noble metal	iron	7439-89-6	0.229	0.06		601		
	inorganic material	phosphorus	7723-14-0	0.069	0.02		180		
	non noble metal	copper	7440-50-8	228.946	60.00	60.08	599930	600711	
wire	non noble metal	aluminium	7429-90-5	0.418	0.11	0.11	1095	1095	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.734	0.45		4545		
	plastics	brominated resin	-	1.858	0.49		4870		
	organic material	carbon black	1333-86-4	1.982	0.52		5194		
	plastics	epoxy resin	-	16.725	4.38		43828		
	inorganic material	silicondioxide	60676-86-0	101.592	26.62	32.46	266211	324648	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9800	9800	
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1333	1333	
solder	noble metal	silver	7440-22-4	0.058	0.02		153		
	non noble metal	tin	7440-31-5	0.047	0.01		122		
	non noble metal	lead	7439-92-1	2.231	0.58	0.61	5846	6121	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.00		50		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.03	5.03	50253	50318	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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